

Simulation of Meniscus Motion and Evaporation for Convective Deposition Manufacturing

Junfeng Xiao and Daniel Attinger

Laboratory for Microscale Transport Phenomena,
Department of Mechanical Engineering,
Columbia University, New York, NY 10027



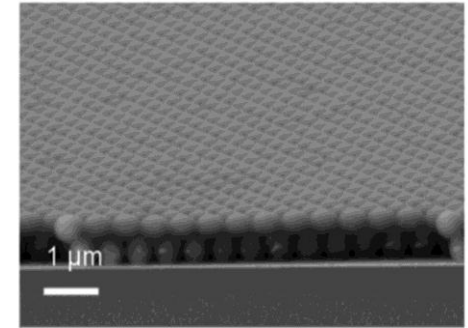
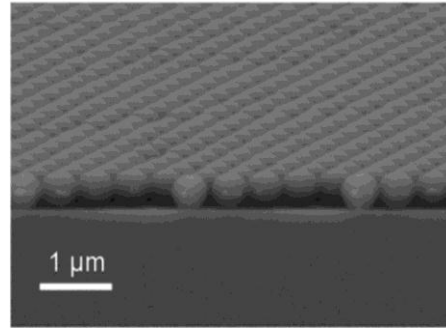
www.me.columbia.edu/lmtp

Laboratory for Microscale
LMTTP
Transport Phenomena

Introduction to Particle Coating

Modify properties of surface

- Optical properties
- Magnetic properties
- Reactivity



Malaquin, L., et al., *Langmuir*, **23**(23): p.11513-11521, (2007).

How to fabricate uniform particle coating?

•Dip coating

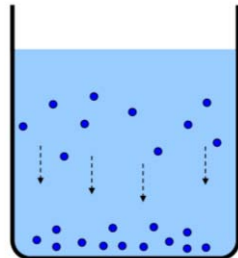
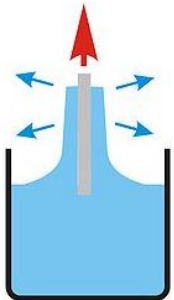
•Sedimentation

•Spin coating

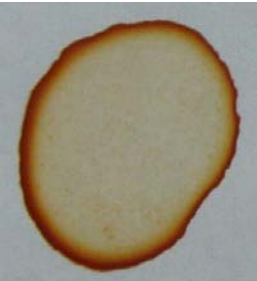
•Convective deposition

•Electrostatic assembly

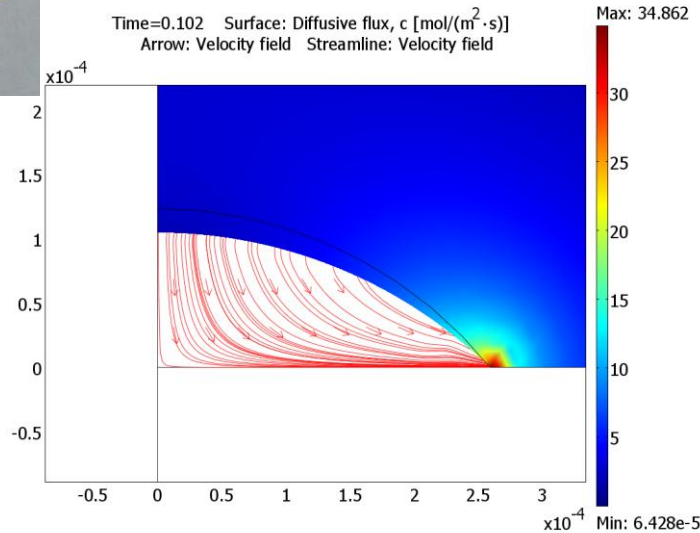
.....



Convective Deposition

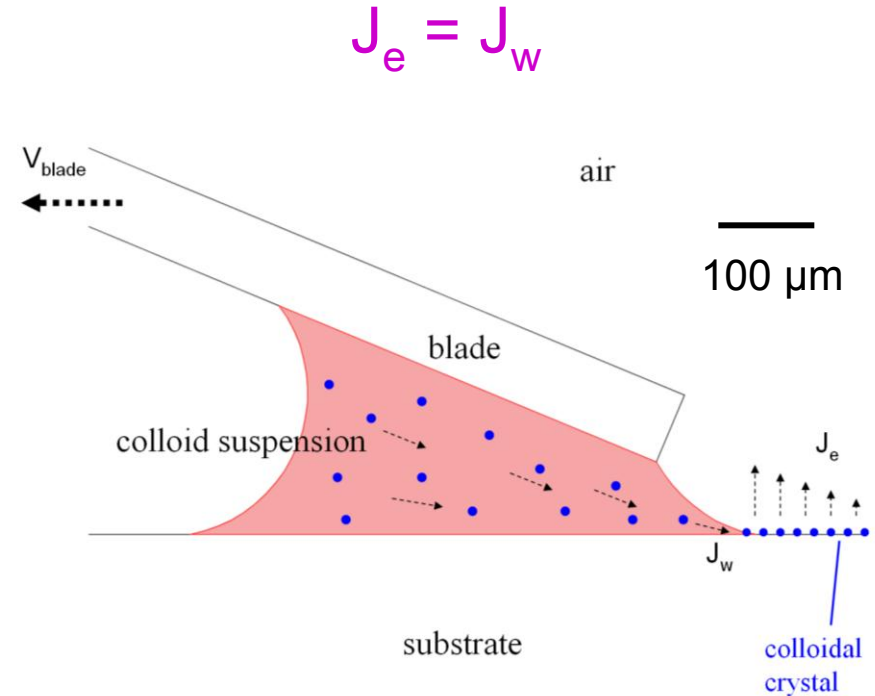


coffee ring effect



2D axi-symmetrical model of an evaporating droplet

evaporation-driven convection



*Deegan, R.D., et al., *Nature*, **389**(6653): p.827-829, 1997.

Parameters that affect the process:

- Properties of liquid
- Volume fraction of particles
- Particle size
- Particle material
- Velocity of blade
- Height of the blade
- Angle of blade
- Temperature of substrate
- Humidity of air
- ...

Multiphysics Modeling

	Governing Equations	Initial Conditions
<p>Moving Mesh (ALE)</p> <p>Active in all domains</p>	$\frac{\partial^2 X}{\partial x^2} + \frac{\partial^2 X}{\partial y^2} = 0$ $\frac{\partial^2 Y}{\partial x^2} + \frac{\partial^2 Y}{\partial y^2} = 0$	<p>$x(0) = \text{xinit_ale}$</p> <p>$y(0) = \text{yinit_ale}$</p> <p>$x_t(0) = 0$</p> <p>$y_t(0) = 0$</p>
<p>Fluid Dynamics</p> <p>Active in liquid domains</p>	$\rho \left(\frac{\partial \mathbf{v}}{\partial t} + \mathbf{v} \cdot \nabla \mathbf{v} \right) = \nabla \cdot \boldsymbol{\sigma} + \mathbf{F}$ $\nabla \cdot \mathbf{v} = \frac{\partial u}{\partial x} + \frac{\partial v}{\partial y} = 0$	<p>$u(0) = 0$</p> <p>$v(0) = 0$</p> <p>$p(0) = -2\gamma/r$</p>
<p>Heat Transfer</p> <p>Active in liquid and substrate domains</p>	$\rho C \left(\frac{\partial T}{\partial t} + \mathbf{v} \cdot \nabla T \right) = k \nabla^2 T$	<p>Liquid: $T(0) = 25^\circ\text{C}$</p> <p>Substrate: $T(0) = T_s$</p>
<p>Mass Transport</p> <p>Active in air domains</p>	$D \nabla^2 c = 0$	<p>$c(0) = 1.3075 * RH \text{ [mol/m}^3\text{]}$</p>

Multiphysics Modeling

Boundary Conditions

Moving Mesh (ALE)

Horizontal boundaries: $dx = 0$

Vertical boundaries: $dy = 0$

Blade: $v_x = V_{\text{blade}}, v_y = 0$

Free surface: $\mathbf{v}_{\text{int}} \cdot \mathbf{n} = (\mathbf{v} - \frac{\mathbf{j}}{\rho}) \cdot \mathbf{n}$

Fluid Dynamics

Liquid/substrate : slip/no-slip

Liquid/blade: $u = V_{\text{blade}}, v = 0$

Free surface: $\boldsymbol{\sigma} \cdot \mathbf{n} = -(2\gamma H + p_0)\mathbf{n}$

Heat Transfer

Far end of substrate: $T = T_s$

Exposed boundary: thermal insulation

Free surface: $j_L = -k\nabla T \cdot \mathbf{n}$

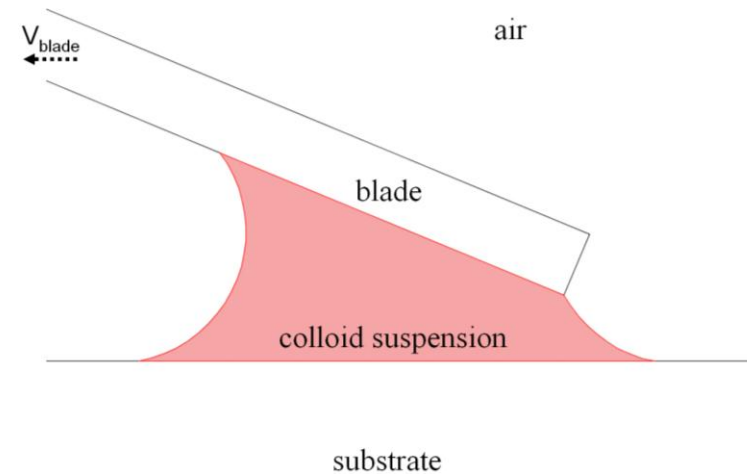
Liquid/substrate: continuity

Mass Transport

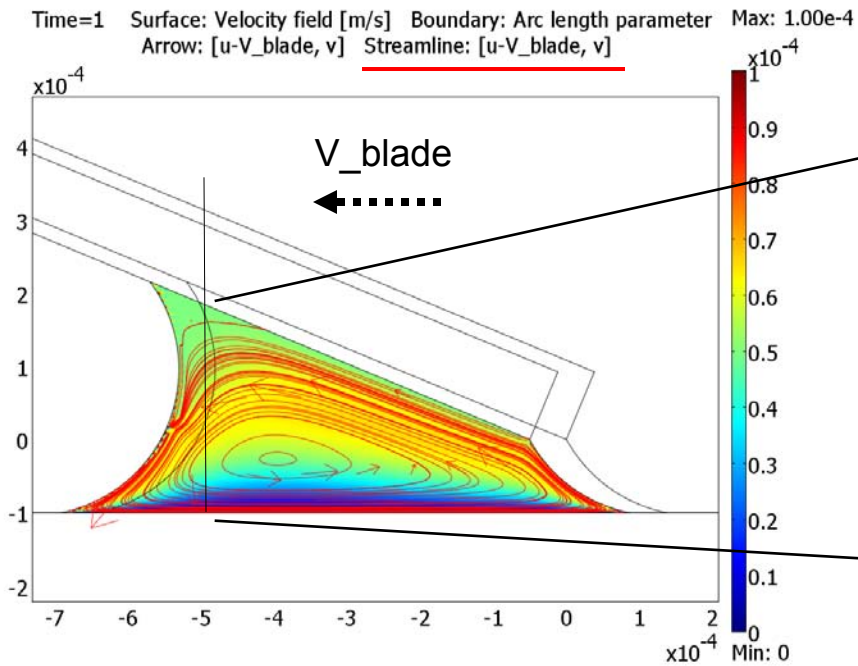
Far end of air: $c = 1.3075 \cdot RH$ [mol/m³]

Exposed boundary: insulation

Free surface: $c = c(t)$

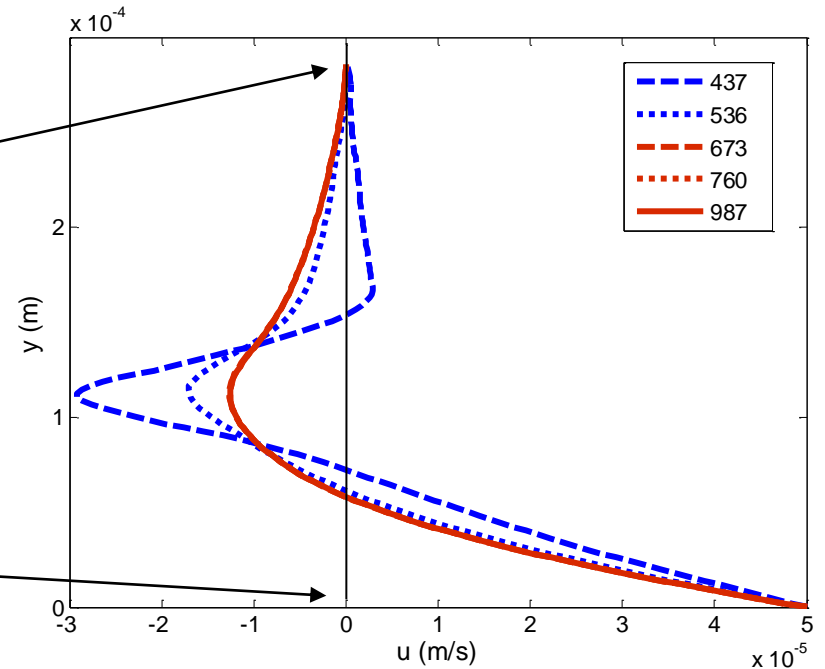


Results – Flow Pattern



Flow pattern in liquid domain

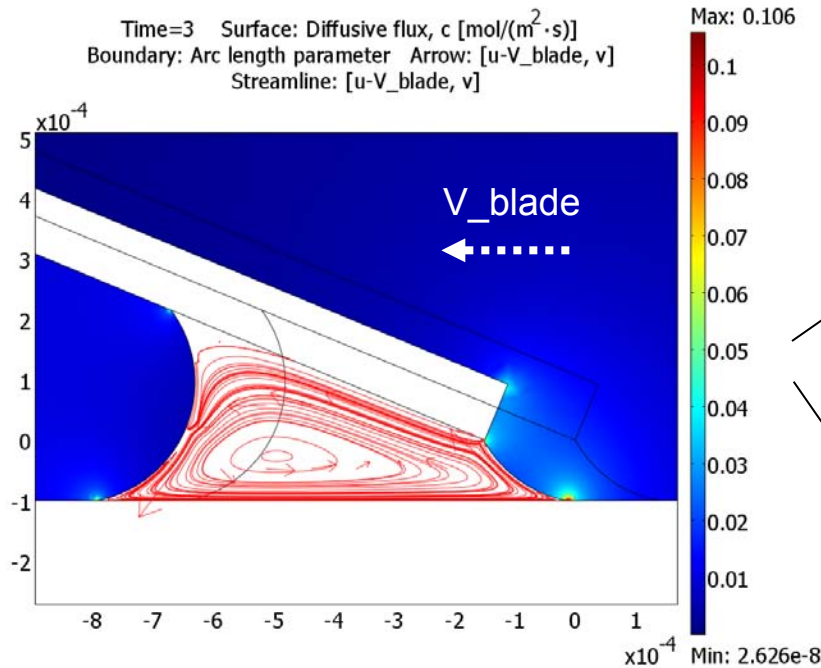
$V_{blade} = 50 \mu\text{m/s}$



Velocity along the red line as a function of mesh size

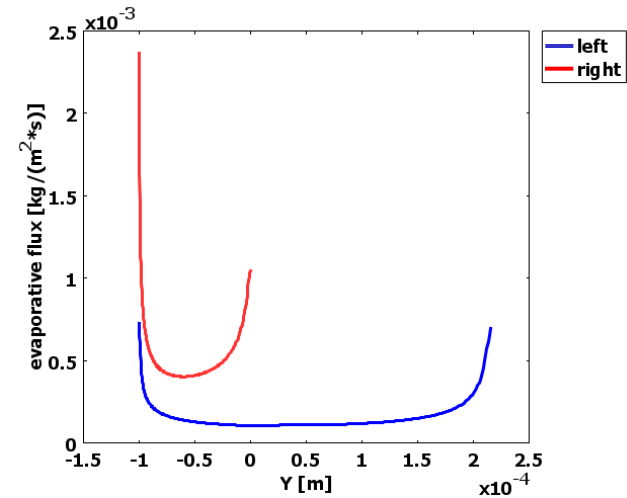
- Shear flow due to the no-slip boundary conditions on blade and substrate
- Low Reynolds number, $Re \sim 0.01$

Results – Evaporation Flux



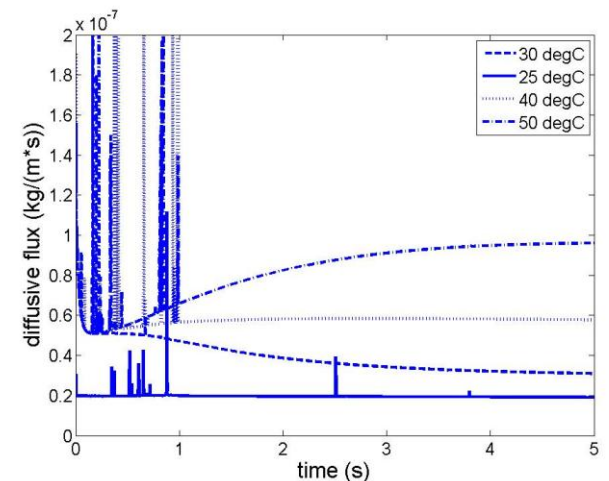
Evaporative flux around free surface
 substrate temperature 50°C, $V_{blade} = 50 \mu\text{m/s}$, $t = 3 \text{ s}$

$j(y)$



evaporative flux at free surface,
 $T_s = 50^\circ\text{C}$, $V_{blade} = 50 \mu\text{m/s}$, $t = 5 \text{ s}$

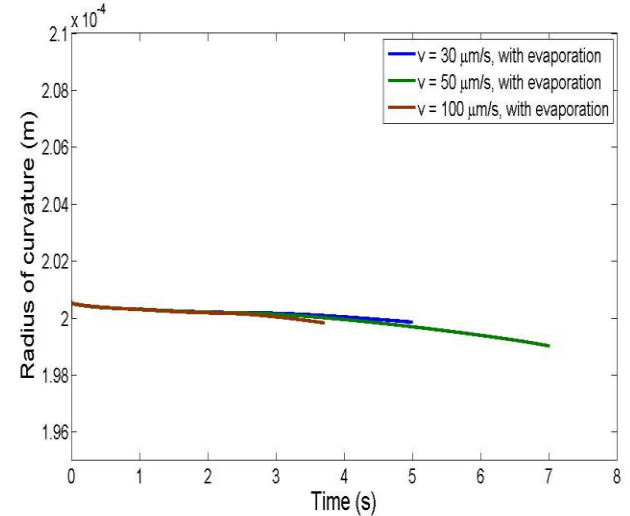
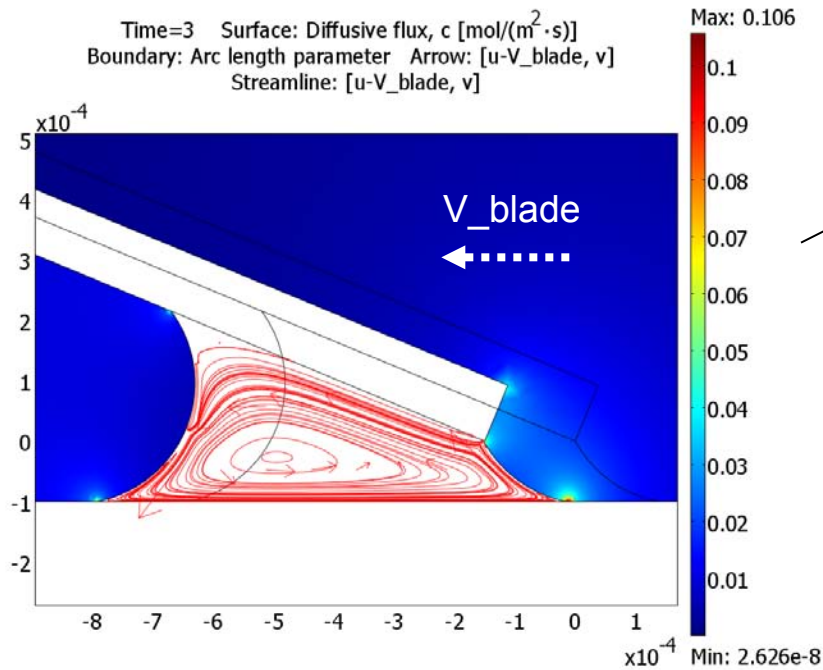
$j(T_s)$



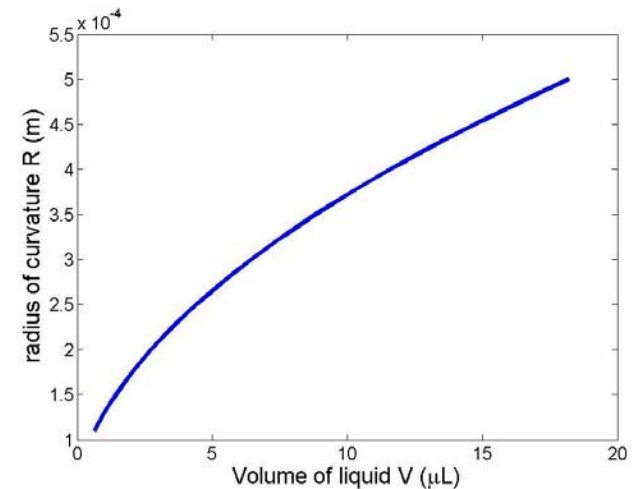
Boundary integral of evaporative flux at right
 free surface, $T_s = 50^\circ\text{C}$, $V_{blade} = 50 \mu\text{m/s}$

- Strongest evaporation flux at contact line
- Evaporation is stronger at right free surface
- Evaporation flux is dependant on substrate temperature

Results – Radius of Curvature



Radius of curvature at free surface



Radius of curvature changes with volume of liquid

Evaporative flux around free surface

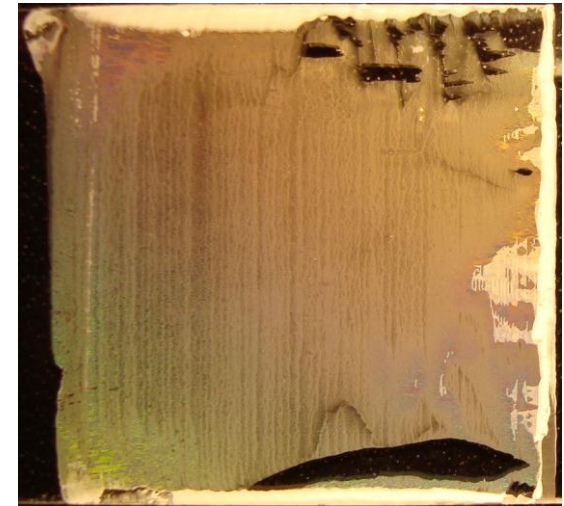
substrate temperature 50°C, $V_{blade} = 50 \mu\text{m/s}$, $t = 3 \text{ s}$

• Radius of curvature at free surface is decreasing as liquid domain is shrinking

Conclusion

- Solve coupled fluid dynamics, heat transfer and mass transfer in a changing geometry for convective deposition using moving mesh (ALE) method
- Special focus has been put on the free surface, such as mesh movement at free surface and evaporation at free surface
- Show flow pattern in the liquid domain with moving and deforming boundaries
- Predict the evaporation rate along the free surface
- Predict the evolution of radius of curvature at free surface

Future Work



Reference

1. Malaquin, L., et al., Controlled Particle Placement through Convective and Capillary Assembly, *Langmuir*, **23**(23): p. 11513-11521, (2007).
2. Deegan, R.D., et al., Capillary flow as the cause of ring stains from dried liquid drops, *Nature*, **389**(6653): p. 827-829, (1997).

Thanks for your attention!



www.me.columbia.edu/lmtp

Laboratory for Microscale
LMTP
Transport Phenomena